DUSEU

MOSFET – N-Channel, QFET

100 V, 70 A, 23 m Ω

FQA70N10

Description

This N-Channel enhancement mode power MOSFET is produced using onsemi's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

Features

- 70 A, 100 V, $R_{DS(on)} = 23 \text{ m}\Omega$ (Max.) @ $V_{GS} = 10 \text{ V}$, $I_D = 35 \text{ A}$
- Low Gate Charge (Typ. 85 nC)
- Low C_{rss} (Typ. 150 pF)
- 100% Avalanche Tested
- 175 °C Maximum Junction Temperature Rating
- This is a Pb–Free Device

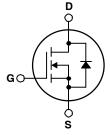
ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{DSS}	Drain to Source Voltage	100	V
۱ _D	$ \begin{array}{ll} \text{Drain Current} & -\text{Continuous } (T_C = 25^\circ\text{C}) \\ & -\text{Continuous } (T_C = 100^\circ\text{C}) \end{array} $	70 49.5	A A
I _{DM}	Drain Current -Pulsed (Note 1)	280	А
V _{GSS}	Gate-Source Voltage	±25	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	1300	mJ
I _{AR}	Avalanche Current (Note 1)	70	А
E _{AR}	Repetitive Avalanche Energy (Note 1)	21.4	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	6.0	V/ns
P _D	Power Dissipation (T _C = 25°C) –Derate Above 25°C	214 1.43	W W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	–55 to +175	°C
TL	Maximum Lead Temperature for Soldering Purposes, 1/8" from Case for 5 seconds	300	°C

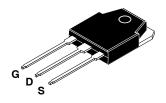
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature. 2. L = 0.4 mH, $I_{AS} = 70 \text{ A}$, $V_{DD} = 25 \text{ V}$, $R_G = 25 \Omega$, Starting $T_J = 25 \text{ °C}$. 3. $I_{SD} \le 70 \text{ A}$, $di/dt \le 300 \text{ A/}\mu\text{s}$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25 \text{ °C}$.

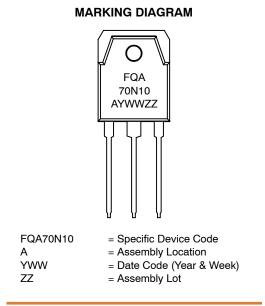
V _{DSS}	R _{DS(on)} MAX	I _D MAX	
100 V	23 mΩ @ 10 V	70 A	



N-CHANNEL MOSFET



TO-3P-3LD CASE 340BZ



ORDERING INFORMATION

Device	Package	Shipping
FQA70N10	TO-3P-3LD (Pb-Free)	450 Units / Tube

THERMAL CHARACTERISTICS

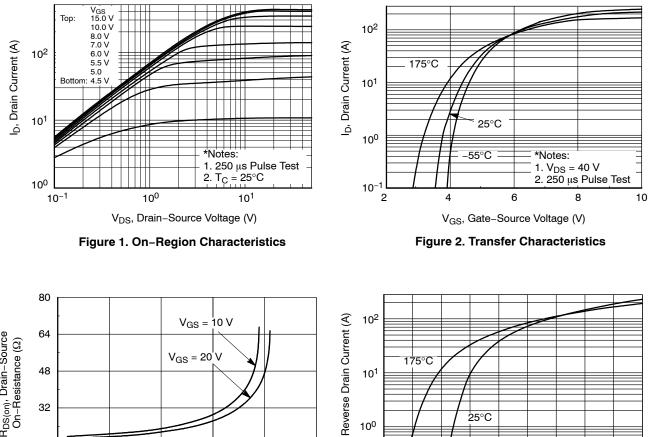
Symbol	Parameter	Value	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case, Max.	0.7	°C/W
R _{0JA}	Thermal Resistance, Junction-to-Ambient, Max.	40	°C/W

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
OFF CHARA	ACTERISTICS	•	-	-		-
BV _{DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0 \ V$	100	-	-	V
$\Delta {\sf BV}_{\sf DSS}$ / $\Delta {\sf T}_{\sf J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 µA, Referenced to 25°C	-	0.1	_	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 100 V, V_{GS} = 0 V	-	-	1	μΑ
		$V_{DS} = 80 \text{ V}, \text{ T}_{C} = 150^{\circ}\text{C}$	-	-	10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 25 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -25 V, V_{DS} = 0 V	_	-	-100	nA
ON CHARA	CTERISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2.0	-	4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 35 \text{ A}$	-	0.019	0.023	Ω
9fs	Forward Transconductance	$V_{DS} = 40 \text{ V}, \text{ I}_{D} = 35 \text{ A}$	-	48	-	S
DYNAMIC C	HARACTERISTICS					
C _{iss}	Input Capacitance	V_{DS} = 25 V, V_{GS} = 0 V, f = 1.0 MHz	-	2500	3300	pF
C _{oss}	Output Capacitance		-	720	940	pF
C _{rss}	Reverse Transfer Capacitance		-	150	200	pF
SWITCHING	CHARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 50 \text{ V}, \text{ I}_{D} = 70 \text{ A},$	-	30	70	ns
t _r	Turn–On Rise Time	R _G = 25 Ω (Note 4)	-	470	950	ns
t _{d(off)}	Turn-Off Delay Time		-	130	270	ns
t _f	Turn-Off Fall Time	1	-	160	330	ns
Qg	Total Gate Charge	$V_{DS} = 80 \text{ V}, \text{ I}_{D} = 70 \text{ A},$	-	85	110	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V (Note 4)	-	16	-	nC
Q _{gd}	Gate-Drain Charge		-	42	-	nC
DRAIN-SOU	RCE DIODE CHARACTERISTICS AND N	IAXIMUM RATINGS				
۱ _S	Maximum Continuous Drain-Source Diode Forward Current		-	-	70	А
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		-	-	280	А
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 70 A	-	-	1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 V, I_S = 70 A,$	-	110	-	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/μs	-	430	-	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
4. Essentially Independent of Operating Temperature.

TYPICAL CHARACTERISTICS (continued)



175°C

10¹

10⁰

10

0.2

0.4

0.6

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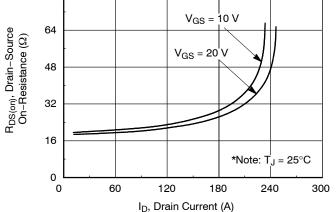


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

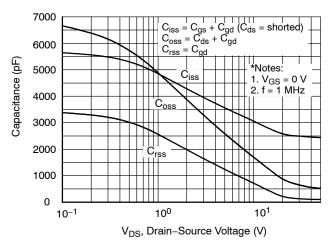


Figure 5. Capacitance Characteristics

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

V_{SD}, Source–Drain Voltage (V)

1.2

*Notes:

1. V_{GS} = 0 V

2. 250 µs Pulse Test

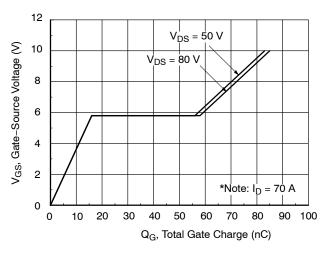
1.8

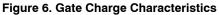
2.0

1.4 1.6

25°C

0.8 1.0





TYPICAL CHARACTERISTICS

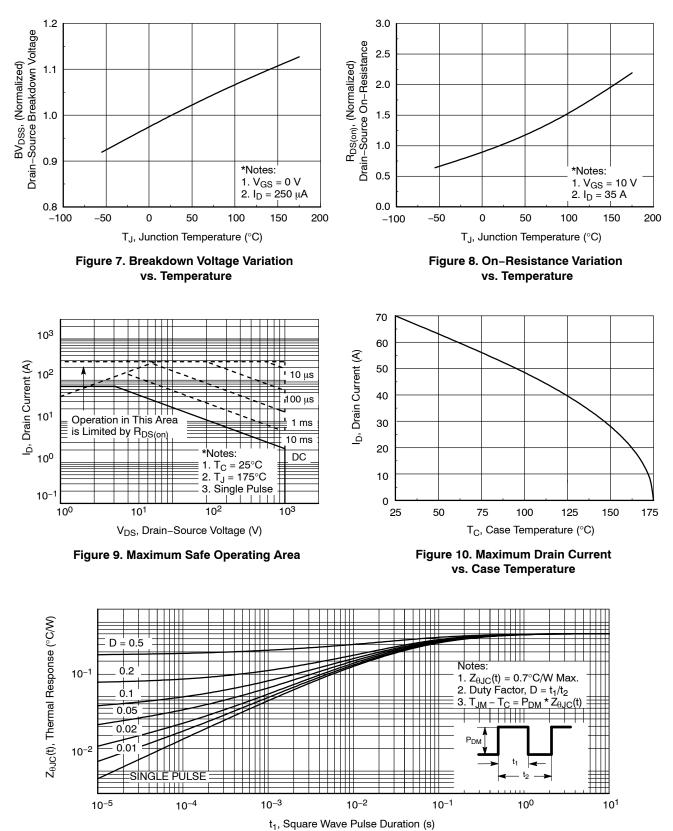


Figure 11. Transient Thermal Response Curve

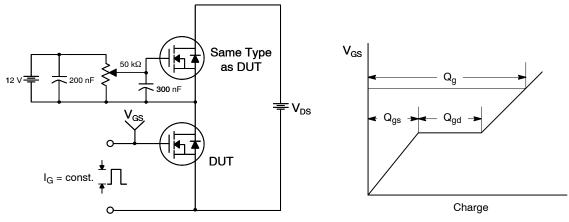


Figure 12. Gate Charge Test Circuit & Waveform

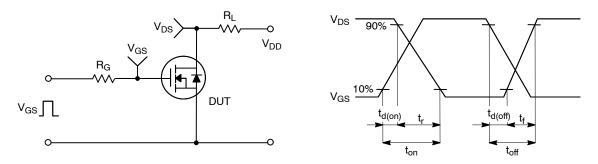


Figure 13. Resistive Switching Test Circuit & Waveforms

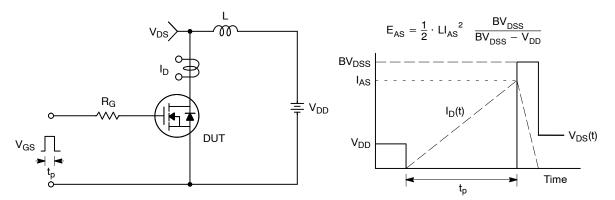
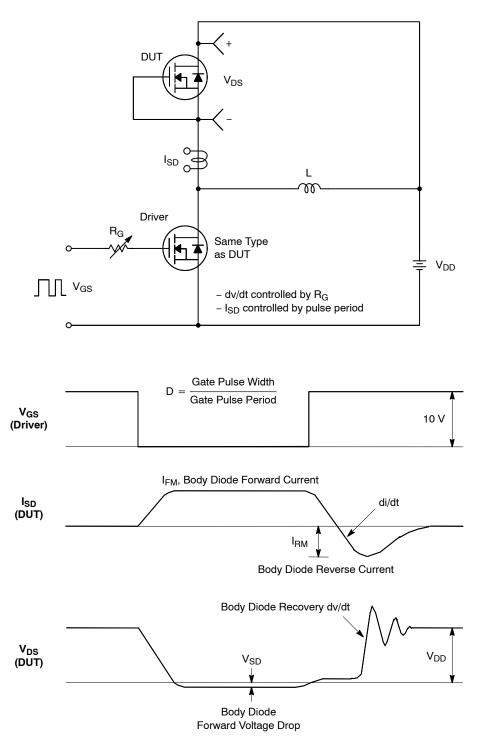
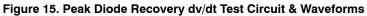
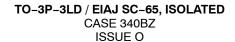


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

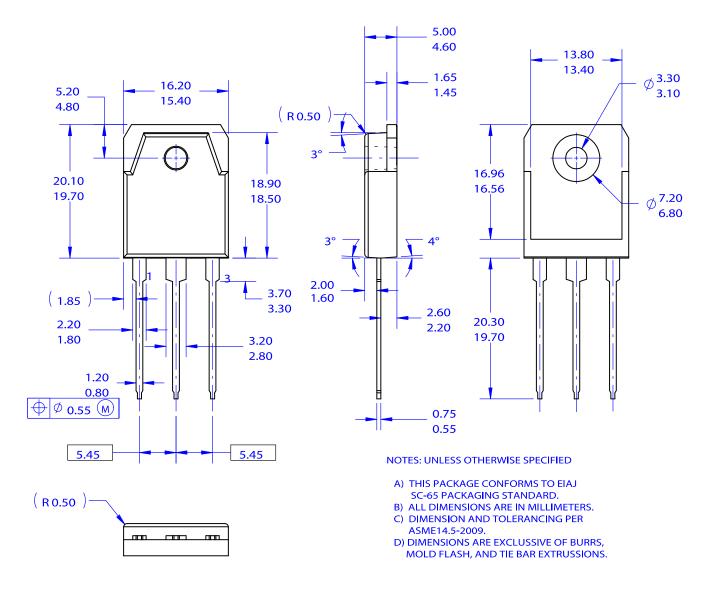








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